



Product Change Notification / RMES-15ZREP293

Date:

15-Jan-2021

Product Category:

Memory

PCN Type:

Manufacturing Change

Notification Subject:

CCB 3379.002 and CCB 3280.001 Final Notice: Qualification of MTAI as an additional assembly and final test site for selected Atmel AT24C0xD, AT24C16D and AT24C32E device families available in 8L SOIC packages.

Affected CPNs:

[RMES-15ZREP293_Affected_CPN_01152021.pdf](#)

[RMES-15ZREP293_Affected_CPN_01152021.csv](#)

Notification Text:

PCN Status: Final notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change: Qualification of MTAI as an additional assembly and final test site for selected Atmel AT24C0xD, AT24C16D and AT24C32E device families available in 8L SOIC packages.

Pre Change:

Assembled at ANAP assembly site using palladium coated copper (PdCu) bond wire, 8290 die attach and G700LS mold compound material with NiPdAu lead plating in 60 x 60 mils paddle size without lead lock.**or** Assembled at ASSH assembly site using palladium coated copper with gold flash (CuPdAu) bond wire, EN-4900GC die attach and CEL-9240HF10AK mold compound material with Matte tin lead plating in 93 x 93 mils paddle size without lead lock.**and**

Tested at ASSH or ANAP Final Test site.

Post Change:

Assembled at ANAP assembly site using palladium coated copper (PdCu) bond wire, 8290 die attach and G700LS mold compound material with NiPdAu lead plating in 60 x 60 mils paddle size without lead lock. **or**

Assembled at ASSH assembly site using palladium coated copper with gold flash (CuPdAu) bond wire, EN-4900GC die attach and CEL-9240HF10AK mold compound material with Matte tin lead plating in 93 x 93 mils paddle size without lead lock.

or Assembled at MTAI assembly site using gold (Au) bond wire, 8390A die attach and G600V mold compound material with Matte tin lead plating in 90 x 90 mils paddle size with lead lock. **and**

Tested at ASSH, ANAP or MTAI Final Test site.

Pre and Post Change Summary:

		Pre Change		Post Change		
Assembly Site		Amkor Technology Philippines (P1/P2), INC. (ANAP)	ASE Advanced Semiconductor (Shanghai) Co., Ltd. (ASSH)	Amkor Technology Philippines (P1/P2), INC. (ANAP)	ASE Advanced Semiconductor (Shanghai) Co., Ltd. (ASSH)	Microchip Technology Thailand (HQ) (MTAI)
Wire material		PdCu	CuPdAu	PdCu	CuPdAu	Au
Die attach material		8290	EN-4900GC	8290	EN-4900GC	8390A
Molding compound material		G700LS	CEL-9240HF10AK	G700LS	CEL-9240HF10AK	G600V
Lead frame material		CDA194	CDA194	CDA194	CDA194	CDA194
Paddle size		60 x 60 mils	93 x 93 mils	60 x 60 mils	93 x 93 mils	90 x 90 mils
Lead Lock		No	No	No	No	Yes
Lead Plating		NiPdAu	Matte tin	NiPdAu	Matte tin	Matte Tin
		Pre Change		Post Change		
Final Test Site		ASE Advanced Semiconductor (Shanghai) Co., Ltd. (ASSH)	Amkor Technology Philippines (P1/P2), INC. (ANAP)	ASE Advanced Semiconductor (Shanghai) Co., Ltd. (ASSH)	Amkor Technology Philippines (P1/P2), INC. (ANAP)	Microchip Technology Thailand (MTAI)
Base Quantity Multiple (BQM)	Tube	100	100	100	100	100
	Tape and Reel	4000	4000	4000	4000	4000
Pin1 Orientation	Tube	Pin 1 side (Black)	Not Applicable	Pin 1 side (Black)	Not Applicable	Pin 1 side (White)
	Tape and Reel	Quadrant 1	Quadrant 1	Quadrant 1	Quadrant 1	Quadrant 1
Tube		Minor dimensional changes – see attachment				

Carrier Tape	No change
Cover Tape	Minor dimensional changes – see attachment
Plastic Reel	Minor dimensional changes – see attachment
Packing Procedure for Tube and Tape & Reel	See attachment

Impacts to Data Sheet: None

Change Impact: None

Reason for Change: To improve on-time delivery performance by qualifying MTAI as an additional assembly and final test site

Change Implementation Status: In Progress

Estimated First Ship Date: February 15, 2021 (date code: 2108)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	January 2021					February 2021				
Workweek	01	02	03	04	05	06	07	08	09	10
Qual Report Availability			X							
Final PCN Issue Date			X							
Estimated First Ship Date								X		

Method to Identify Change: Traceability code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report. PCN_RMES-15ZREP293_Qual_Report – Assembly sitePCN_RMES-15ZREP293_Qual_Report – Final Test site

Revision History: January 15, 2021: Issued final notification. Attached the qualification report. Provided estimated first ship date to be on February 15, 2021.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_RMES-15ZREP293_Qual_Report - Assembly Site.pdf](#)

[PCN_RMES-15ZREP293_Qual_Report - Final Test.pdf](#)

[PCN_RMES-15ZREP293_Pre and Post Change Summary.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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